



AI TECHNOLOGY INC
 70 Washington Road
 Princeton Jct., NJ 08550
 (609) 799-9388 fax (609) 799-9308
 E-Mail: ait@aitechnology.com
 Internet: <http://www.aitechnology.com>

PRIMA-BOND
ME7265-2 PART

- Extra Clean in Ionics
- Solvent-Free
- Electrically Insulating
- Thermally Conductive

IDEAL FOR:

- High Thermal Dissipation
- Die and Component Attach
- Automated Assembly

DESCRIPTION:

ME7265-2 PART is a 2 parts packaged version of ME7265 for ease of international shipping and/or ambient storage. Once mixed in 2/1 ratio by weight for PART A to PART B, it is a rapid curing thermally conductive and insulating epoxy adhesive for die and substrate attach applications. This paste is solvent free. It is designed for automated, inline bonding processing. Its is engineered to combine high bond strength and molecular flexibility that helps to absorb interfacial stresses for long-term reliability.

ME7265 is low in ionic impurities and meets all requirements for MIL-Std 883 Method 5011.5 specification for dielectric adhesive.

AVAILABILITY:

ME7265-2 PART is available in jars of different sizes at PART A to PART B ratio of 2 to 1 by weight.

APPLICATION PROCEDURES:

(1) Mix 2 parts by weight of PART A to 1 part by weight of PART B thoroughly. Make sure bubbles are minimized during mixing. Acetone may be used to lower the viscosity to allow the bubbles to burst.

(2) If acetone is used in assisting mixing, please allow at least 60 minutes to allow acetone to evaporate before using.

(3) Dispense adhesive onto clean substrate with a suitable pattern to assure full die coverage.

(4) Cure according to one of the recommended cure schedules.

TYPICAL PROPERTIES*

| | |
|---|---|
| Electrical Resistivity (150°C/ 30 min) | >1x10 ¹⁴ ohm-cm |
| Dielectric Strength (Volts/mil) | >750 |
| Glass Transition Temp.(°C) | 75 ±10% |
| Current Carrying Capabilities | |
| Lap-Shear Strength | >1000 psi >6.87 N/mm ² |
| Device Push-off Strength | >2400 psi >16.6 N/mm ² |
| Hardness (Type) | 70 (D) ±10% |
| Cured Density (gm/cc) | 1.8 ±10% |
| Thermal Conductivity | 7.0 Btu-in/hr-ft ² -°f ±10% 1.0 W/m-°C ±10% |
| Linear Thermal Expansion | 45 ±15% |
| Coeff. (ppm/°C) | |
| Maximum Continuous Operation Temp. (°C) | <150 |
| Pot Life | >7 days0 minutes |
| Avg. Viscosity(5.0 rpm, 25°C) | 50,000 cp ±20% |
| (Brookfield DV-1,Spindle CP51) | |
| Thixotropic Index | 3.0±20% |

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

CURE SCHEDULES:

| Temperature | Time | Pressure |
|-------------|--------|----------|
| 100°C | 4 hr | |
| 125°C | 90 min | |
| 150°C | 30 min | |
| 175°C | 10 min | |

After mixing PART A to PART B in 2/1 ratio by weight, ambient floor life (pot-life) is 5 days or more.

SHELF LIFE:

| Storage temperature | Shelf Life |
|---------------------------|------------|
| <40°C ar before mixing | 12 mo |

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.

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